

Title (en)
BATCH FURNACE

Title (de)
BATCH-OFEN

Title (fr)
FOUR DE CUISSON PAR LOTS

Publication
EP 1540708 A2 20050615 (EN)

Application
EP 03766990 A 20030730

Priority
• US 0323849 W 20030730
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Abstract (en)
[origin: WO2004013901A2] A system and method for isothermally distributing a temperature across a semiconductor device. A furnace assembly is provided, which includes a processing tube configured to removably receive a wafer carrier having a full compliment of semiconductor wafers. A heating assembly is provided which can include a heating element positioned to heat air or other gases allowed to enter the process tube. The furnace assembly and process tube are capable of being vertically raised and lowered into a position enclosing the heating assembly within the process tube. Once the heating assembly forms a seal with the process tube, the process tube is exhausted and purged of air. Gas is then allowed to flow into the process tube and exchange heat with the heating element. The heated gas circulates through the process tube to convectively change the temperature of the wafers.

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H01L 21/00; **C23C 16/455**; **C23C 16/453**

IPC 8 full level
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CPC (source: EP KR)
C23C 16/46 (2013.01 - EP); **H01L 21/324** (2013.01 - KR); **H01L 21/67109** (2013.01 - EP); **H01L 21/67115** (2013.01 - EP)

Citation (search report)
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